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Part Number: [0717640228](#)
Status: **Active**
Description: 2.54mm (.100") Pitch C-Grid® Breakaway Header, Low Profile, Dual Row, Right Angle, High Temperature, 28 Circuits, 0.76µm (30µ") Gold (Au) Selective Plating

Documents:

3D Model	Product Specification PS-71764 (PDF)
Packaging Specification (PDF)	RoHS Certificate of Compliance (PDF)
Drawing (PDF)	

Agency Certification

CSA	LR19980
UL	E29179

General

Product Family	PCB Headers
Series	71764
Application	Board-to-Board, Wire-to-Board
Product Name	C-Grid®

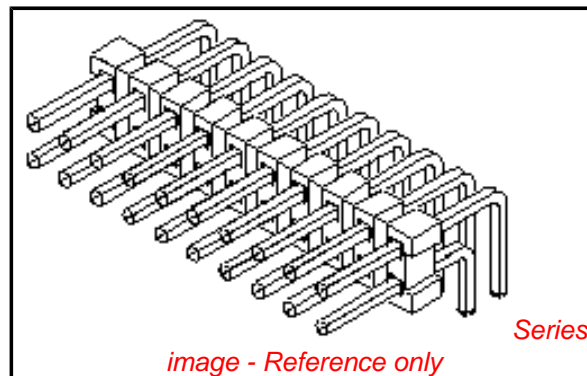
Physical

Breakaway	Yes
Circuits (Loaded)	28
Circuits (maximum)	28
Color - Resin	Black
Durability (mating cycles max)	50
Flammability	94V-0
Glow-Wire Compliant	No
Lock to Mating Part	None
Material - Metal	Brass, Phosphor Bronze
Material - Plating Mating	Gold
Material - Plating Termination	Tin
Material - Resin	High Temperature Thermoplastic
Number of Rows	2
Orientation	Right Angle
PC Tail Length (in)	0.110 In
PC Tail Length (mm)	2.79 mm
PCB Locator	No
PCB Retention	None
Packaging Type	Tube
Pitch - Mating Interface (in)	0.100 In
Pitch - Mating Interface (mm)	2.54 mm
Plating min: Mating (µin)	30
Plating min: Mating (µm)	0.75
Plating min: Termination (µin)	75
Plating min: Termination (µm)	1.875
Polarized to Mating Part	No
Shrouded	No
Stackable	Yes
Temperature Range - Operating	-40°C to +105°C
Termination Interface: Style	Through Hole

Electrical

Current - Maximum per Contact	3A
Voltage - Maximum	250V

Solder Process Data



EU RoHS

ELV and RoHS Compliant
REACH SVHC Contains SVHC: No
Halogen-Free Status
Not Reviewed

China RoHS



Need more information on product environmental compliance?

Email productcompliance@molex.com
 For a multiple part number RoHS Certificate of Compliance, [click here](#)

Please visit the [Contact Us](#) section for any non-product compliance questions.

Search Parts in this Series
[71764Series](#)

Duration at Max. Process Temperature (seconds)	5
Lead-free Process Capability	Wave Capable (TH only)
Max. Cycles at Max. Process Temperature	1
Process Temperature max. C	260

Material Info

Reference - Drawing Numbers

Product Specification	PS-71764
Sales Drawing	SD-71764-001

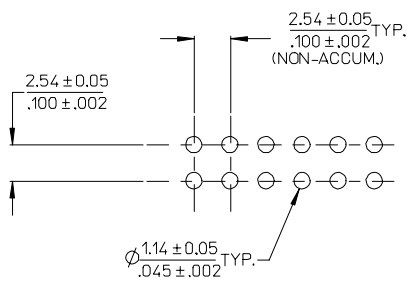
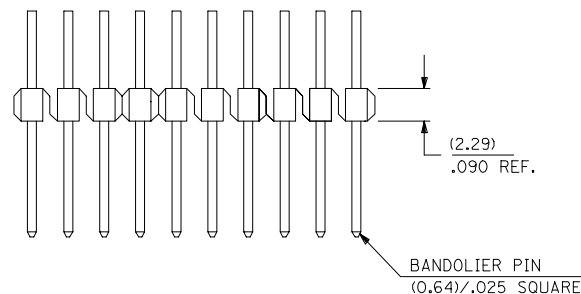
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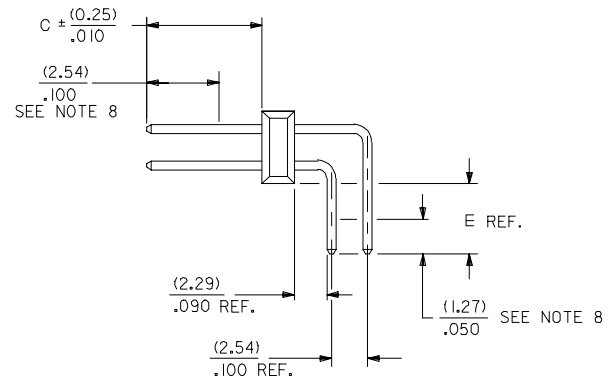
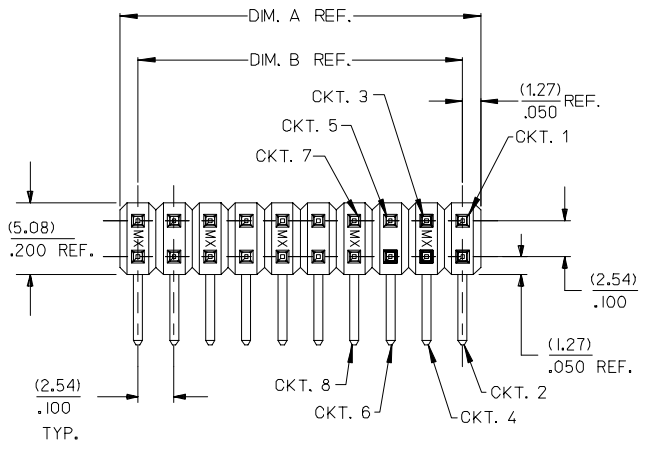
13 12 11 10 9 8 7 6 5 4 3 2 1

J
I
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A

CKTS	DIM. A	DIM. B
04	(5.08)/.200	(2.54)/.100
06	(7.62)/.300	(5.08)/.200
08	(10.16)/.400	(7.62)/.300
10	(12.70)/.500	(10.16)/.400
12	(15.24)/.600	(12.70)/.500
14	(17.78)/.700	(15.24)/.600
16	(20.32)/.800	(17.78)/.700
18	(22.86)/.900	(20.32)/.800
20	(25.40)/1.000	(22.86)/.900
22	(27.94)/1.100	(25.40)/1.000
24	(30.48)/1.200	(27.94)/1.100
26	(33.02)/1.300	(30.48)/1.200
28	(35.56)/1.400	(33.02)/1.300
30	(38.10)/1.500	(35.56)/1.400



RECOMMENDED P.C. BOARD HOLE LAYOUT



- NOTES:
- MATERIAL: WAFER - HIGH TEMPERATURE THERMAL PLASTIC, 94V-0; COLOR: BLACK
PIN - COPPER ALLOY
 - PLATING:
TIN - (0.00381)/.000150 MINIMUM TIN PLATE OVER NICKEL PLATE.
15 GOLD - (0.00038)/.000015 MINIMUM GOLD PLATE IN SELECT AREA.
(0.00191)/.000075 MINIMUM TIN PLATE IN SELECT AREA, OVER NICKEL PLATE OVERALL.
30 GOLD - (0.00076)/.000030 MINIMUM GOLD PLATE IN SELECT AREA.
(0.00191)/.000075 MINIMUM TIN PLATE IN SELECT AREA, OVER NICKEL PLATE OVERALL.
 - * THE PRIMARY SHIPPING CARTON WILL BE LABELD 'COMPLIANT TO RoHS DIRECTIVE 2002/95/EC AND ELV ANNEX II OF DIRECTIVE 2000/53/EC'. CARTONS WITHOUT THIS LABEL MAY CONTAIN PRODUCT WITH LEAD.
 - PRODUCT CONFORMS TO PS-71764.
 - PACKAGING INFORMATION:
FOR 4 THRU 8 CIRCUIT PARTS USE PK-70873-0353
FOR 10 CIRCUITS AND OVER USE PK-70873-0075
 - FOR ILLUSTRATION PURPOSES, 20 (DUAL 10) CIRCUIT SIZE IS SHOWN.
 - PINS MUST MEET SOLDERABILITY SPEC. ES-152, EXCEPT VOIDS ARE PERMISSIBLE AT BANDOLIER PIN AT BANDOLIER PIN FAYING SURFACE. (APPROX. (0.64)/.025 LNG X (0.15)/.006 WD. REF.) 2 LOCATIONS
 - WAFER TO BE FLAT WITHIN (0.03 MM/CM) OR .003 IN./IN
 - MEASURE POINT FOR PLATING THICKNESS.
 - THIS PART CONFORMS TO CLASS B REQUIREMENTS OF COSMETIC SPECIFICATION PS-45499-002

2	A
1	A1
SHT.	REV.

ADD NOTE 9 EC NO: UCP2007-1441 DRAWN/PRD/DR 2006/12/11 CHKD:ADERR 2006/12/11 APPR:FSM TH 2006/12/12	QUALITY SYMBOLS =0 =0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM/IN		SCALE 4:1	DESIGN UNITS INCH	THIRD ANGLE PROJECTION
		mm	INCH	DRAWN BY CAC	DATE 1995/08/23	TITLE DUAL ROW WAFER ASS'Y W/BREAK-OFF OPTION RT. ANG. (0.64)/.025 SQ PINS		
A1	REVISION	4 PLACES ± --- ± ---	3 PLACES ± --- ± .01	CHECKED BY PR	DATE 1995/08/23	MATERIAL NO. DOCUMENT NO.		SHEET NO. 1 OF *
		2 PLACES ± 0.25 ± .01	1 PLACE ± 0.25 ± ---	APPROVED BY DJB	DATE 1995/08/23	MOLEX INCORPORATED		
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		ANGULAR ±1/2°		SEE TABLE		SD-71764-001		
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION								

12 11 10 9 8 7 6 5 4 3 2 1

ITEM NO: 71764-0004/0030, 9003			ITEM NO: 71764-0104/0130, 9001, 9004			ITEM NO: 71764-0204/0230, 9000, 9002		
DIM. C		(6.10)/.240	DIM. C		(6.10)/.240	DIM. C		(6.10)/.240
DIM. E (REF.)		(2.79)/.110	DIM. E (REF.)		(2.79)/.110	DIM. E (REF.)		(2.79)/.110
FINISH		TIN	FINISH		15 GOLD	PLATING FINISH		30 GOLD
CONNECTOR END PLATING		TIN	CONNECTOR END PLATING		GOLD	CONNECTOR END PLATING		GOLD
P.C. BOARD END PLATING		TIN	P.C. BOARD END PLATING		TIN	P.C. BOARD END PLATING		TIN
PACKAGING		SEE NOTE 4 SHEET 1	PACKAGING		SEE NOTE 4 SHEET 1	PACKAGING		SEE NOTE 4 SHEET 1
CKTS	ITEM NUMBER	VOIDS	CKTS	ITEM NUMBER	VOIDS	CKTS	ITEM NUMBER	VOIDS
04	71764-0004		04	71764-0104		04	71764-0204	
06	71764-0006		06	71764-0106		06	71764-0206	
08	71764-0008		08	71764-0108		08	71764-0208	
10	71764-0010		10	71764-0110		10	71764-0210	
12	71764-0012		12	71764-0112		12	71764-0212	
14	71764-0014		14	71764-0114		14	71764-0214	
16	71764-0016		16	71764-0116		16	71764-0216	
18	71764-0018		18	71764-0118		18	71764-0218	
20	71764-0020		20	71764-0120		20	71764-0220	
22	71764-0022		22	71764-0122		22	71764-0222	
24	71764-0024		24	71764-0124		24	71764-0224	
26	71764-0026		26	71764-0126		26	71764-0226	
28	71764-0028		28	71764-0128		28	71764-0228	
30	71764-0030		30	71764-0130		30	71764-0230	
06	71764-9003	3	06	71764-9001	3, 4	06	71764-9002	3, 4
			08	71764-9004	5, 6			
						10	71764-9000	8

A	REV:	ECR/ECN INFORMATION	TITLE:	DUAL ROW WAFER ASS'Y W/ BREAK-OFF OPTION RT. ANG. (0.64)/.025 SQ PINS	SHEET No.
		EC No: UCP2007-0449			- 2 -
		DATE: 2006-08-18			
DOCUMENT NUMBER:		CREATED / REVISED BY:	CHECKED BY:	APPROVED BY:	
SD-71764-001		PRIDDER	ADERR	FSMITH	

ITEM NO: 71764-0304/0330		
DIM. C	(8.13)/.320	
DIM. E (REF.)	(2.79)/.110	
PLATING FINISH	TIN	
CONNECTOR END PLATING	TIN	
P.C. BOARD END PLATING	TIN	
PACKAGING	SEE NOTE 4 SHEET 1	
CKTS	ITEM NUMBER	VOIDS
04	71764-0304	
06	71764-0306	
08	71764-0308	
10	71764-0310	
12	71764-0312	
14	71764-0314	
16	71764-0316	
18	71764-0318	
20	71764-0320	
22	71764-0322	
24	71764-0324	
26	71764-0326	
28	71764-0328	
30	71764-0330	

ITEM NO: 71764-0404/0430		
DIM. C	(8.13)/.320	
DIM. E (REF.)	(2.79)/.110	
PLATING FINISH	15 GOLD	
CONNECTOR END PLATING	GOLD	
P.C. BOARD END PLATING	TIN	
PACKAGING	SEE NOTE 4 SHEET 1	
CKTS	ITEM NUMBER	VOIDS
04	71764-0404	
06	71764-0406	
08	71764-0408	
10	71764-0410	
12	71764-0412	
14	71764-0414	
16	71764-0416	
18	71764-0418	
20	71764-0420	
22	71764-0422	
24	71764-0424	
26	71764-0426	
28	71764-0428	
30	71764-0430	

ITEM NO: 71764-0504/0530		
DIM. C	(8.13)/.320	
DIM. E (REF.)	(2.79)/.110	
PLATING FINISH	30 GOLD	
CONNECTOR END PLATING	GOLD	
P.C. BOARD END PLATING	TIN	
PACKAGING	SEE NOTE 4 SHEET 1	
CKTS	ITEM NUMBER	VOIDS
04	71764-0504	
06	71764-0506	
08	71764-0508	
10	71764-0510	
12	71764-0512	
14	71764-0514	
16	71764-0516	
18	71764-0518	
20	71764-0520	
22	71764-0522	
24	71764-0524	
26	71764-0526	
28	71764-0528	
30	71764-0530	

REV: A	ECR/ECN INFORMATION	TITLE: DUAL ROW WAFER ASS'Y W/ BREAK-OFF OPTION RT. ANG. (0.64)/.025 SQ PINS	SHEET No.
	EC No: UCP2007-0449		- 3 -
	DATE: 2006-08-18		
DOCUMENT NUMBER: SD-71764-001	CREATED / REVISED BY: PRIDDER	CHECKED BY: ADERR	APPROVED BY: FSMITH